

H-Bridge Drivers for DC Brush Motors

Single H-Bridge Driver High-Speed Switching Type

BD63576NUX

General Description

The BD63576NUX provides a single H-bridge motor driver which features wide range of motor power supply voltage from 2.0V to 10.0V and low power consumption to switch low ON-Resistance DMOS transistors at high speed. This small surface mounting package is most suitable for mobile system, home appliance and various applications.

Features

- Low ON-Resistance Power DMOS Output
- Charge Pump-less with PDMOS High Side Driver
- Under Voltage Locked Out Protection and Thermal Shut Down Function
- Automatic Power-Saving Mode Function

Applications

- Mobile System
- Home Appliance
- Amusement System, etc.

Key Specifications

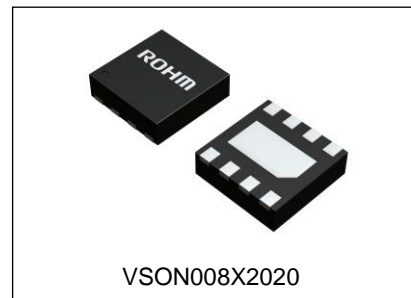
- Power Supply Voltage Range: 2.5V to 5.5V
- Motor Power Supply Voltage Range: 2.0V to 10.0V
- Circuit Current (Short Brake Mode): 150μA(Typ)
- Stand-By Current: 1μA (Max)
- Control Input Voltage Range: 0V to V_{CC}V
- Operation Mode Logic Input Frequency: 20kHz to 500kHz
- Minimum Logic Input Pulse Width: 0.5μs(Min)
- Turn On Time: 240ns(Typ)
- Turn Off Time: 60ns(Typ)
- H-Bridge Output Current (DC): ±1.2A
- H-Bridge Output Current (Peak): ±3.2A
- Output ON-Resistance (Total): 0.55Ω(Typ)
- Operating Temperature Range: -30°C to +85°C

Package

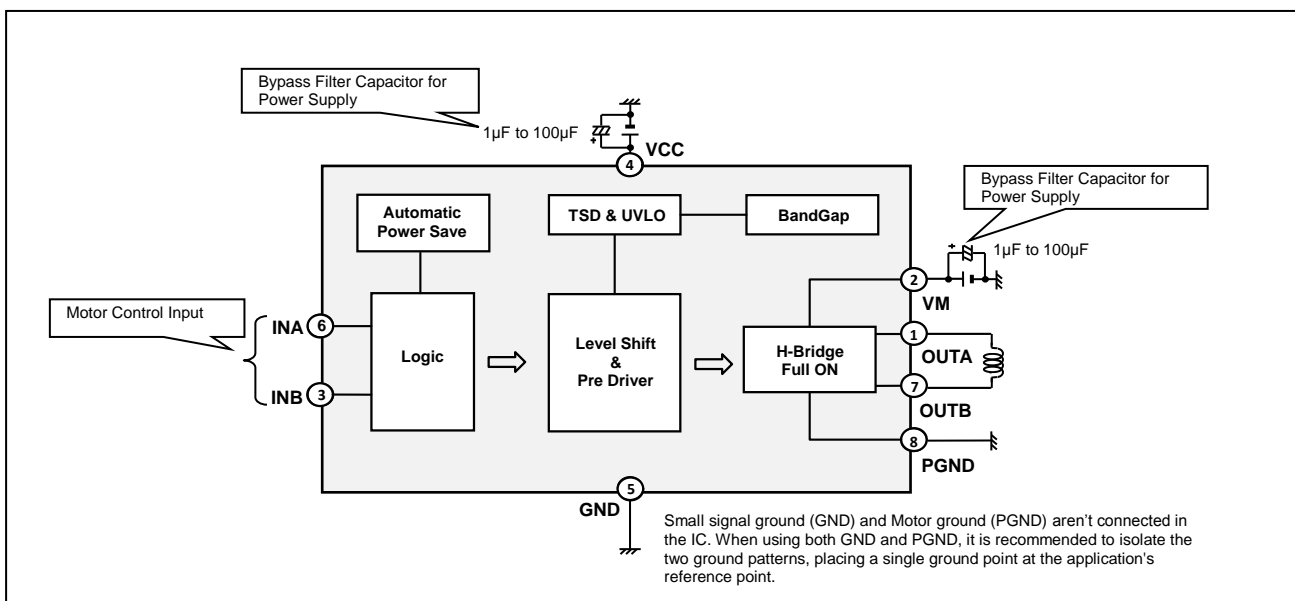
VSON008X2020

W(Typ) x D(Typ) x H(Max)

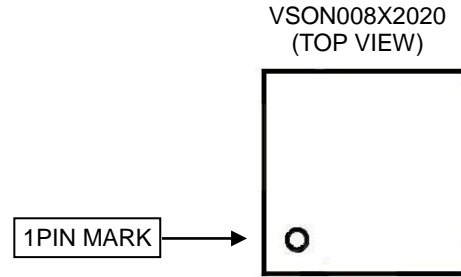
2.00mm x 2.00mm x 0.60mm



Typical Application Circuit



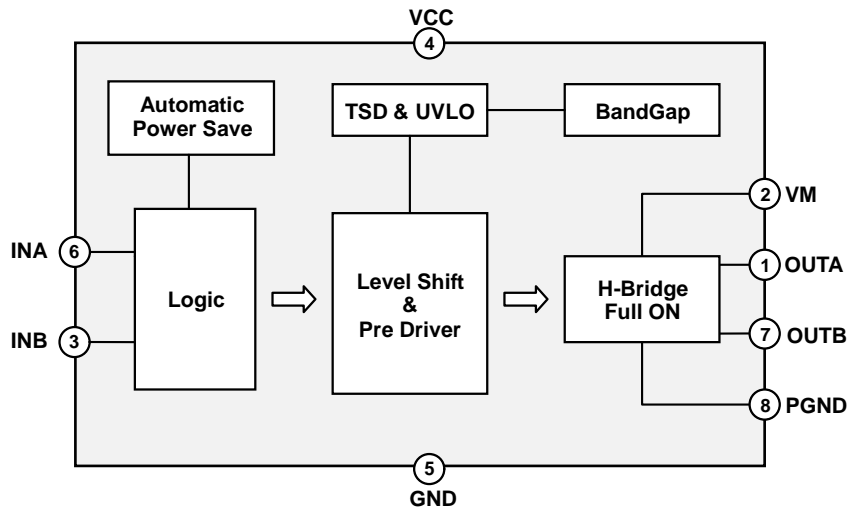
Pin Configuration



Pin Description

Pin No.	Pin Name	Function
1	OUTA	H-Bridge output terminal A
2	VM	Motor power supply terminal
3	INB	Control input terminal B
4	VCC	Power supply terminal
5	GND	Ground terminal
6	INA	Control input terminal A
7	OUTB	H-bridge output terminal B
8	PGND	Motor ground terminal

Block Diagram



Description of Blocks

- Motor Control Input**
 INA and INB Pins
 Logic level controls the output logic of H-Bridge.
 (See the Electrical Characteristics; p.4/15, and I/O Truth Table; p.7/15)
- Automatic Power-Saving Function**
 The automatic power-saving function allows the system to save power when not driving the motor. The device changes state from operating to stand-by when output logic becomes open mode between 50 μ s to 500 μ s. (See the Timing Chart; p.8/15)

Absolute Maximum Ratings (Ta=25°C)

Items	Symbol	Rating	Unit
Power Supply Voltage	V _{CC}	-0.3 to +7.0	V
Motor Power Supply Voltage	V _M	-0.3 to +10.5	V
Control Input Voltage	V _{IN}	-0.3 to V _{CC} +0.3	V
H Bridge Output Current (DC)	I _{OUT}	±1.2 ^(Note 1)	A
H Bridge Output Current (PEAK)	I _{OUT(PEAK)}	±3.2 ^(Note 2)	A
Storing Temperature Range	T _{stg}	-55 to +150	°C
Connections Temperature	T _{jmax}	150	°C

(Note 1) ASO and T_j=150°C should not be exceeded.

(Note 2) PEAK=100 ms (Duty≤5%). ASO and T_j=150°C should not be exceeded.

Caution: Operating the IC over the absolute maximum ratings may damage the IC. The damage can either be a short circuit between pins or an open circuit between pins and the internal circuitry. Therefore, it is important to consider circuit protection measures, such as adding a fuse, in case the IC is operated over the absolute maximum ratings.

Thermal Resistance^(Note 3)

Parameter	Symbol	Thermal Resistance (Typ)		Unit
		1s ^(Note 5)	2s2p ^(Note 6)	
VSON008X2020				
Junction to Ambient	θ _{JA}	309.5	77.1	°C/W
Junction to Top Characterization Parameter ^(Note 4)	Ψ _{JT}	53	12	°C/W

(Note 3) Based on JESD51-2A (Still-Air)

(Note 4) The thermal characterization parameter to report the difference between junction temperature and the temperature at the top center of the outside surface of the component package.

(Note 5) Using a PCB board based on JESD51-3.

Layer Number of Measurement Board	Material	Board Size
Single	FR-4	114.3mm x 76.2mm x 1.57mm

Top	
Copper Pattern	Thickness
Footprints and Traces	70μm

(Note 6) Using a PCB board based to JESD51-5 and 7.

Layer Number of Measurement Board	Material	Board Size	Thermal Via ^(Note 7)		
			Pitch	Diameter	
4 Layers	FR-4	114.3mm x 76.2mm x 1.6mm	1.20mm	Φ0.30mm	
Top		2 Internal Layers		Bottom	
Copper Pattern	Thickness	Copper Pattern	Thickness	Copper Pattern	Thickness
Footprints and Traces	70μm	74.2mm x 74.2mm	35μm	74.2mm x 74.2mm	70μm

(Note 7) This thermal via connects with the copper pattern of all layers.

Recommended Operation Conditions

Items	Symbol	Min	Typ	Max	Unit
Power Supply Voltage	V _{CC}	2.5	-	5.5	V
Motor Power Supply Voltage	V _M	2.0	-	10.0	V
Control Input Voltage	V _{IN}	0	-	V _{CC}	V
Operation Mode Logic Input Frequency	F _{IN}	20	-	500	kHz
Minimum Logic Input Pulse Width	T _{IN}	0.5	-	-	μs
Operation Temperature Range	T _{OPR}	-30	-	+85	°C

Electrical Characteristics (Unless otherwise specified, VCC=3.3V, VM=5.0V, Ta=25°C)

Parameters	Symbol	Min	Typ	Max	Unit	Conditions
All Circuits						
Stand-by Current	I _{CCST}	-	0	1	μA	V _{IN} =0V
Circuit Current 1 ^(NOTE 8)	I _{CC1}	50	135	225	μA	INA=0V↔3.3V (F _{IN} =20kHz, Duty=10%) INB=0V
Circuit Current 2	I _{CC2}	50	145	225	μA	CW & CCW Mode
Circuit Current 3	I _{CC3}	50	150	225	μA	Short Brake Mode
Control Input (IN=INA, INB)						
High-Level Input Voltage	V _{INH}	0.7 × V _{CC}	-	V _{CC}	V	
Low-Level Input Voltage	V _{INL}	0	-	0.3 × V _{CC}	V	
High-Level Input Current	I _{INH}	16	33	66	μA	V _{IN} =3.3V
Low-Level Input Current	I _{INL}	-1	0	+1	μA	V _{IN} =0V
Under Voltage Locked Out (UVLO)						
UVLO Voltage	V _{UVLO}	1.9	-	2.5	V	
Full ON Driver						
Output On-Resistance	R _{ON}	-	0.55	0.75	Ω	I _{OUT} =±500mA, High & Low-side total
Turn On Time	T _{ON}	-	240	400	ns	20Ω Load
Turn Off Time	T _{OFF}	-	60	400	ns	20Ω Load

(Note 8) This is same with condition INB=0V↔3.3V (F_{IN}=20KHz, Duty=10%), INA=0V.

Typical Performance Curves (Reference Data)

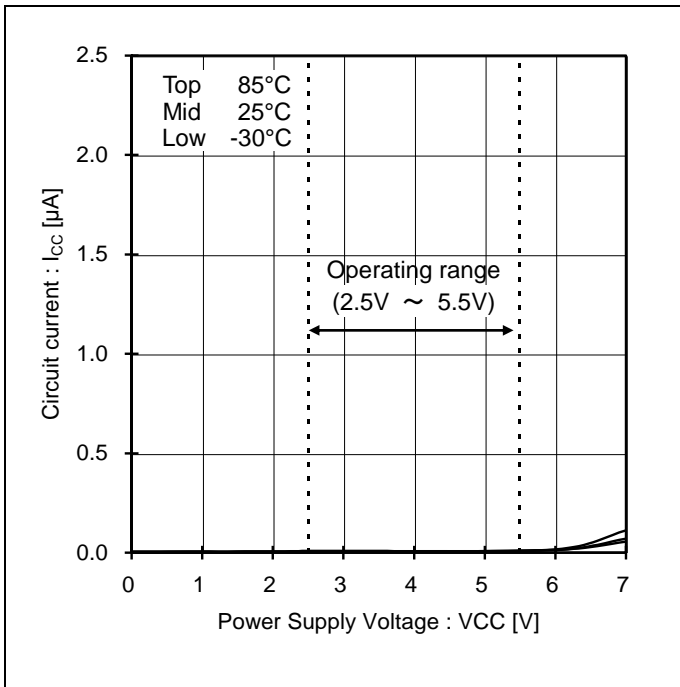


Figure 1.
Circuit Current vs Power Supply Voltage
("Circuit Current", Stand-by Mode)

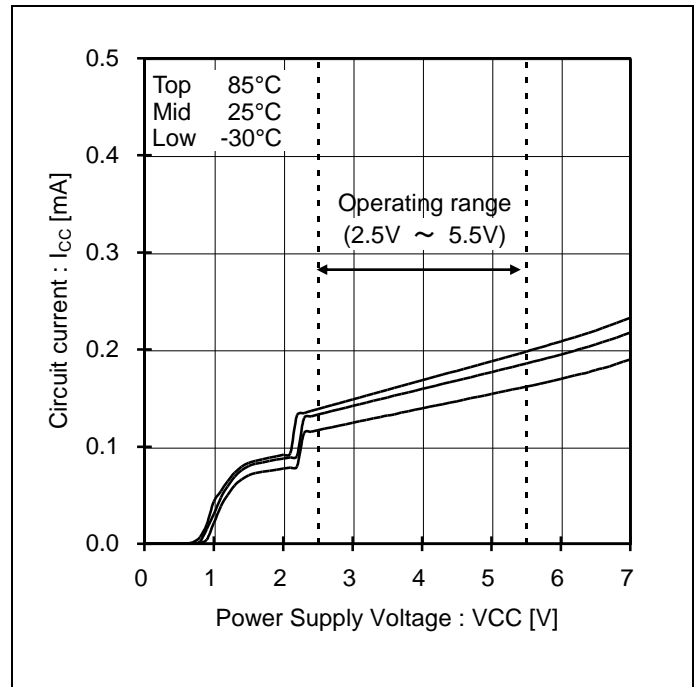


Figure 2.
Circuit Current vs Power Supply Voltage
("Circuit Current", Short Brake Mode)

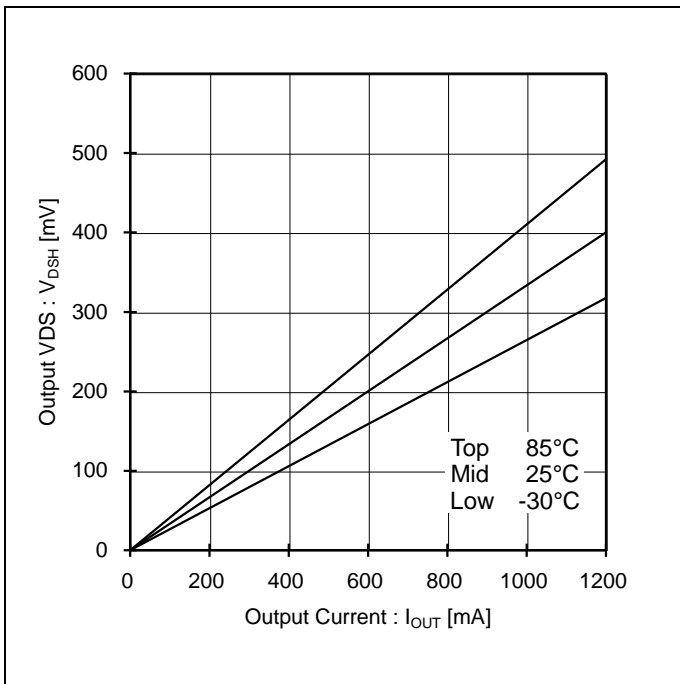


Figure 3.
Output VDS vs Output Current
("Output High-Side On-Resistance", VM=5V and VCC=3.3V)

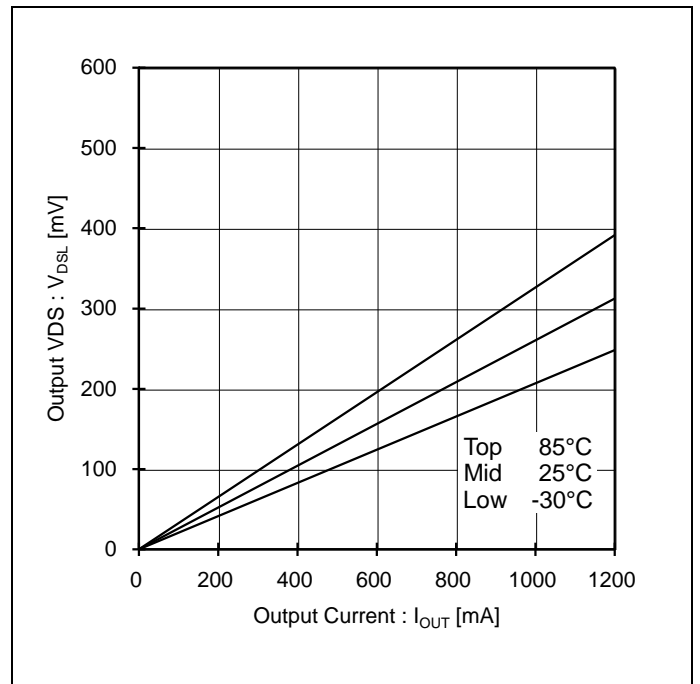


Figure 4.
Output VDS vs Output Current
("Output Low-Side On-Resistance", VM=5V and VCC=3.3V)

Typical Performance Curves (Reference Data) - continued

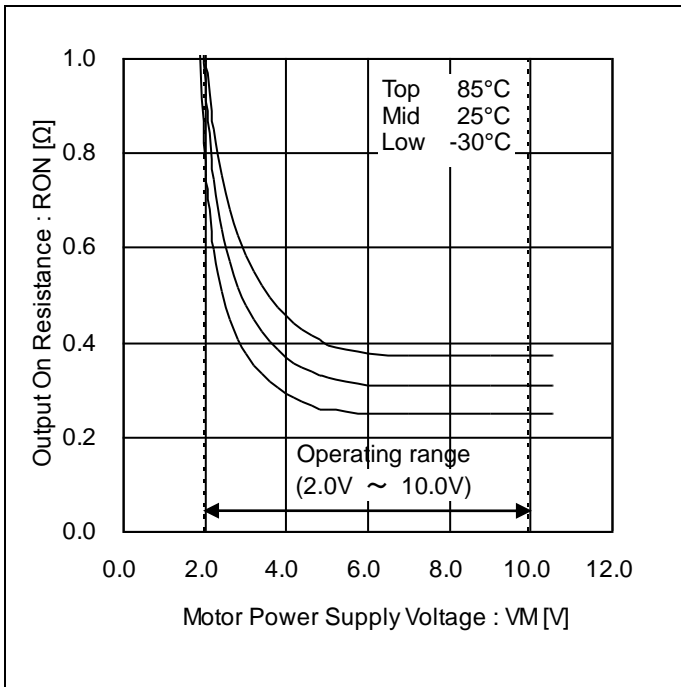


Figure 5.
Output On-Resistance vs Motor Power Supply Voltage
("Output High-Side ON-Resistance VM Dependence",
VCC=3.3V)

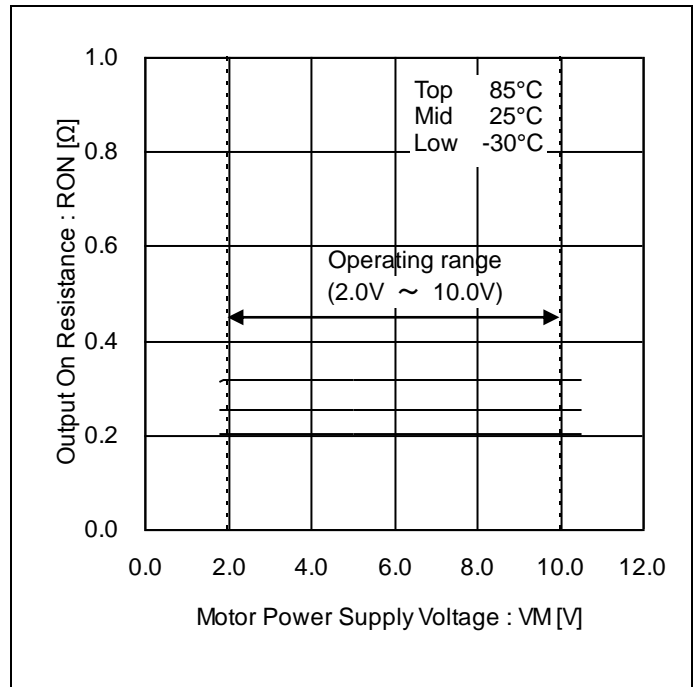


Figure 6.
Output On-Resistance vs Motor Power Supply Voltage
("Output Low-Side On-Resistance VM Dependence",
VCC=3.3V)

Timing Chart

Table1. I/O Truth Table

Input System	INPUT		OUTPUT		
	INA	INB	OUTA	OUTB	Output Mode (Note 9)
IN/IN	L	L	Z	Z	Open
	H	L	H	L	Clockwise
	L	H	L	H	Counter clockwise
	H	H	L	L	Short Brake

L: Low, H: High, X: Don't care, Z: High-Impedance

(Note 9) CW: Current flows from OUTA to OUTB, CCW: Current flows from OUTB to OUTA

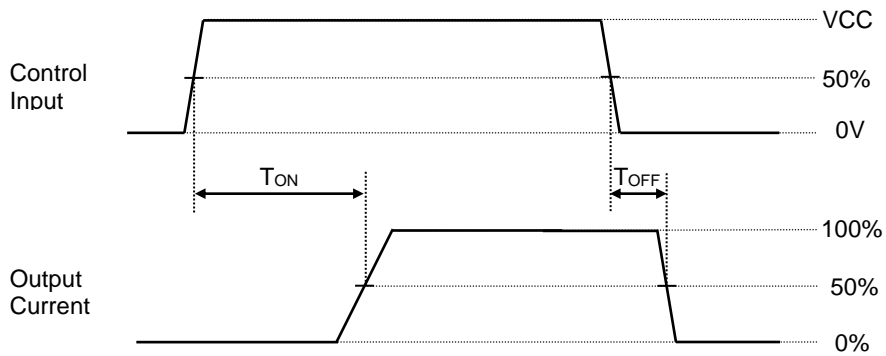
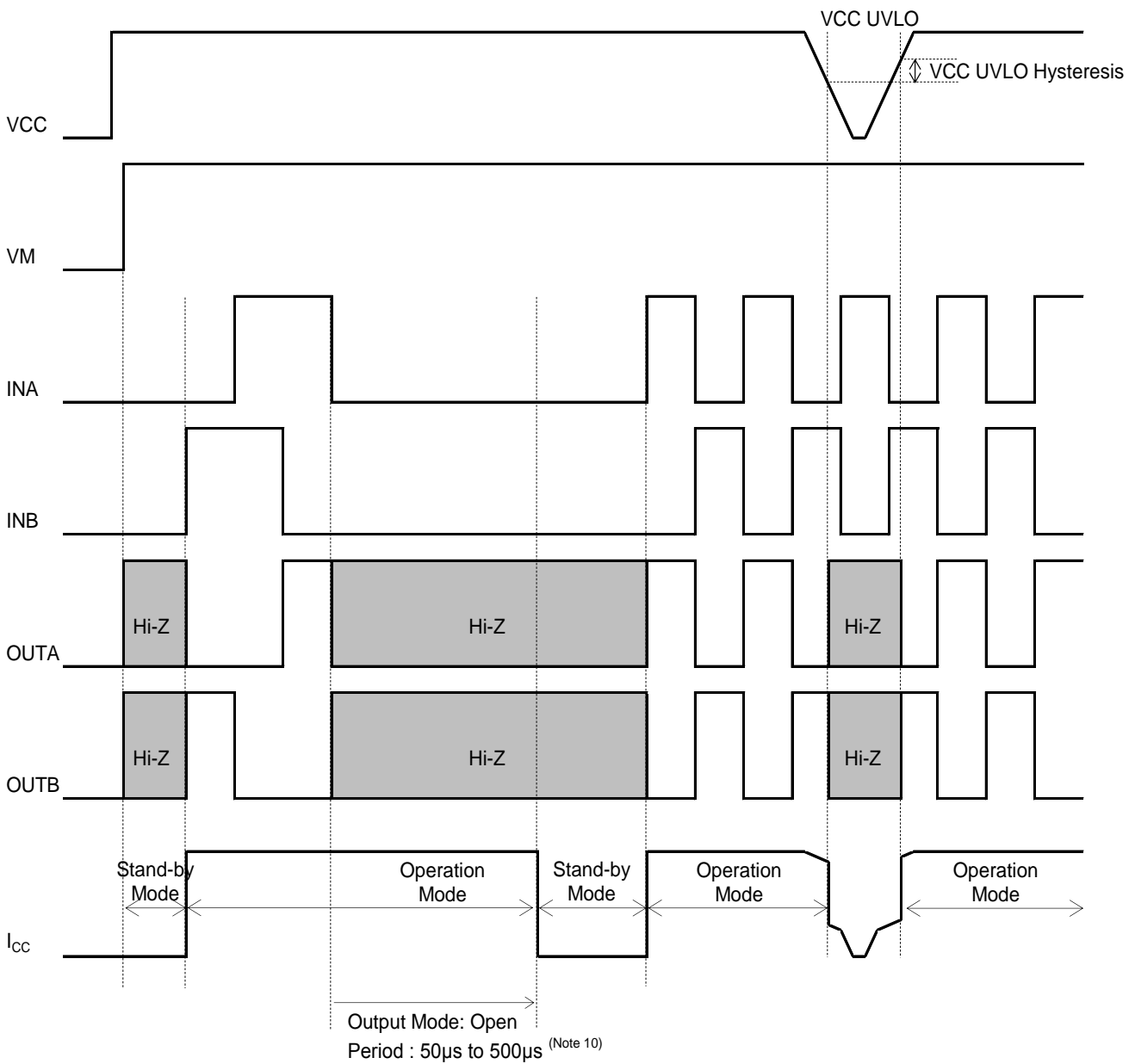


Figure 7.
Input-Output AC Characteristics

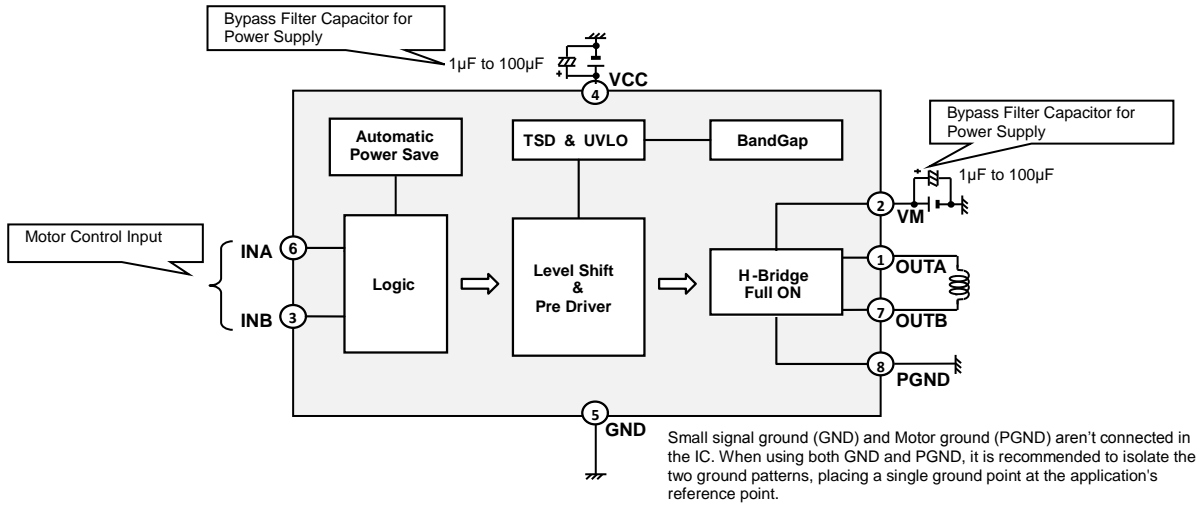
Timing Chart - continued



(Note 10) In PWM drive operation, condition INA=Low and INB=Low must be kept less than 50µs. If condition INA=Low and INB=Low exceeds 500µs period, device will switch to stand-by mode.

Figure 8.
Timing Diagram

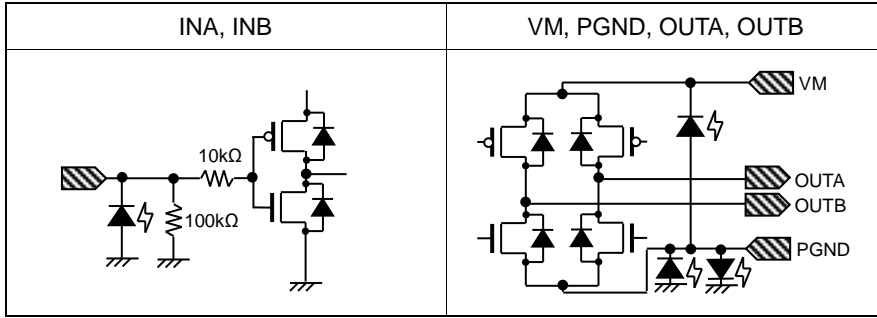
Application Example



Selection of Components Externally Connected

When using the circuit with changes to the external circuit constants, make sure to leave an adequate margin for external components including static and transitional characteristics as well as dispersion of the IC.

I/O Equivalence Circuits



Operational Notes

1. Reverse Connection of Power Supply

Connecting the power supply in reverse polarity can damage the IC. Take precautions against reverse polarity when connecting the power supply, such as mounting an external diode between the power supply and the IC's power supply pins.

2. Power Supply Lines

Design the PCB layout pattern to provide low impedance supply lines. Separate the ground and supply lines of the digital and analog blocks to prevent noise in the ground and supply lines of the digital block from affecting the analog block. Furthermore, connect a capacitor to ground at all power supply pins. Consider the effect of temperature and aging on the capacitance value when using electrolytic capacitors.

3. Ground Voltage

Ensure that no pins are at a voltage below that of the ground pin at any time, even during transient condition.

4. Ground Wiring Pattern

When using both small-signal(GND) and large-current ground(PGND) traces, the two ground traces should be routed separately but connected to a single ground at the reference point of the application board to avoid fluctuations in the small-signal ground caused by large currents. Also ensure that the ground traces of external components do not cause variations on the ground voltage. The ground lines must be as short and thick as possible to reduce line impedance.

5. Thermal Consideration

Should by any chance the power dissipation rating be exceeded the rise in temperature of the chip may result in deterioration of the properties of the chip. In case of exceeding this absolute maximum rating, increase the board size and copper area to prevent exceeding the Pd rating.

6. Recommended Operating Conditions

These conditions represent a range within which the expected characteristics of the IC can be approximately obtained. The electrical characteristics are guaranteed under the conditions of each parameter.

7. Inrush Current

When power is first supplied to the IC, it is possible that the internal logic may be unstable and inrush current may flow instantaneously due to the internal powering sequence and delays, especially if the IC has more than one power supply. Therefore, give special consideration to power coupling capacitance, power wiring, width of ground wiring, and routing of connections.

8. Operation Under Strong Electromagnetic Field

Operating the IC in the presence of a strong electromagnetic field may cause the IC to malfunction.

9. Testing on Application Boards

When testing the IC on an application board, connecting a capacitor directly to a low-impedance output pin may subject the IC to stress. Always discharge capacitors completely after each process or step. The IC's power supply should always be turned off completely before connecting or removing it from the test setup during the inspection process. To prevent damage from static discharge, ground the IC during assembly and use similar precautions during transport and storage.

10. Inter-pin Short and Mounting Errors

Ensure that the direction and position are correct when mounting the IC on the PCB. Incorrect mounting may result in damaging the IC. Avoid nearby pins being shorted to each other especially to ground, power supply and output pin. Inter-pin shorts could be due to many reasons such as metal particles, water droplets (in very humid environment) and unintentional solder bridge deposited in between pins during assembly to name a few.

11. Unused Input Pins

Input pins of an IC are often connected to the gate of a MOS transistor. The gate has extremely high impedance and extremely low capacitance. If left unconnected, the electric field from the outside can easily charge it. The small charge acquired in this way is enough to produce a significant effect on the conduction through the transistor and cause unexpected operation of the IC. So, unless otherwise specified, unused input pins should be connected to the power supply or ground line.

Operational Notes – continued

12. Regarding the Input Pin of the IC

This monolithic IC contains P+ isolation and P substrate layers between adjacent elements in order to keep them isolated. P-N junctions are formed at the intersection of the P layers with the N layers of other elements, creating a parasitic diode or transistor. For example (refer to figure below):

When $GND > Pin\ A$ and $GND > Pin\ B$, the P-N junction operates as a parasitic diode.

When $GND > Pin\ B$, the P-N junction operates as a parasitic transistor.

Parasitic diodes inevitably occur in the structure of the IC. The operation of parasitic diodes can result in mutual interference among circuits, operational faults, or physical damage. Therefore, conditions that cause these diodes to operate, such as applying a voltage lower than the GND voltage to an input pin (and thus to the P substrate) should be avoided.

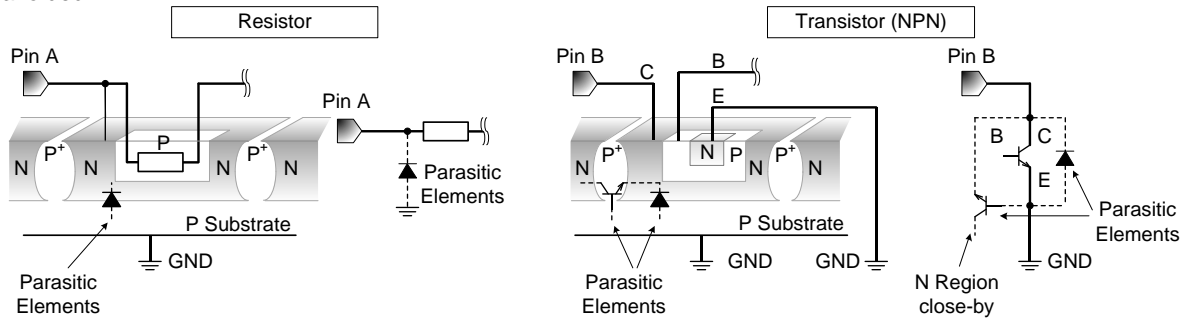


Figure 9.

Example of monolithic IC structure

13. Ceramic Capacitor

When using a ceramic capacitor, determine the dielectric constant considering the change of capacitance with temperature and the decrease in nominal capacitance due to DC bias and others.

14. Area of Safe Operation (ASO)

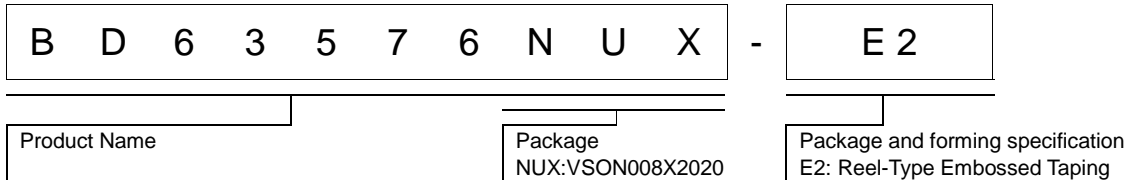
Operate the IC such that the output voltage, output current, and power dissipation are all within the Area of Safe Operation (ASO).

15. Thermal Shutdown Circuit(TSD)

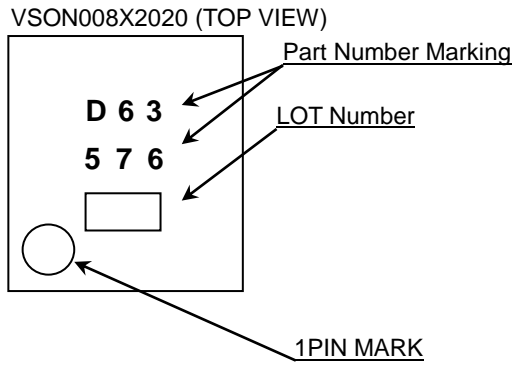
This IC has a built-in thermal shutdown circuit that prevents heat damage to the IC. Normal operation should always be within the IC's power dissipation rating. If however the rating is exceeded for a continued period, the junction temperature (T_j) will rise which will activate the TSD circuit that will turn OFF all output pins. When the T_j falls below the TSD threshold, the circuits are automatically restored to normal operation.

Note that the TSD circuit operates in a situation that exceeds the absolute maximum ratings and therefore, under no circumstances, should the TSD circuit be used in a set design or for any purpose other than protecting the IC from heat damage.

Ordering Information



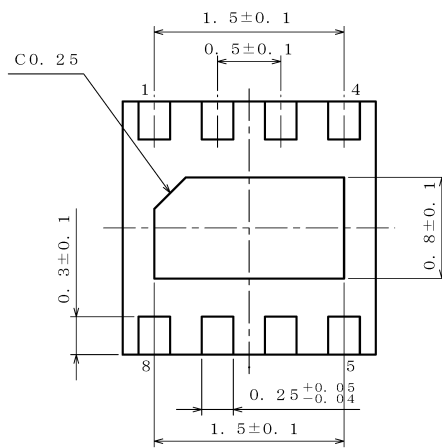
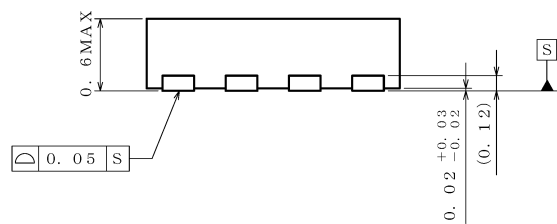
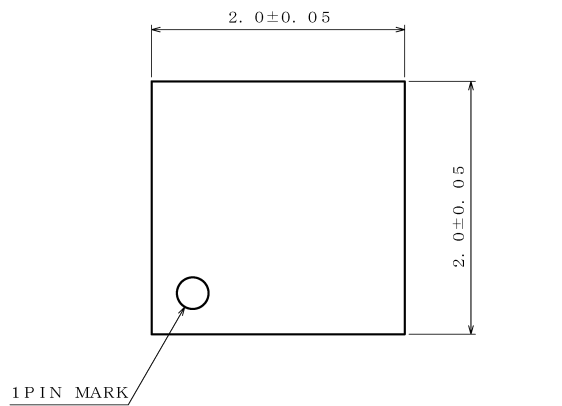
Marking Diagram



Part Number Marking	Package	Orderable Part Number
D63576	VSON008X2020	BD63576NUX-E2

Physical Dimension and Packing Information

Package Name	VSON008X2020
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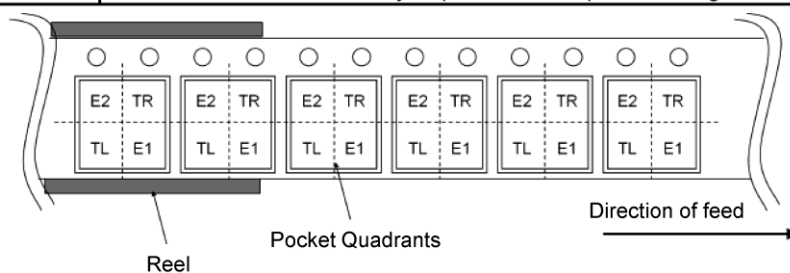


(UNIT : mm)

PKG : VSON008X2020
Drawing No. EX178-5001

< Tape and Reel Information >

Tape	Embossed carrier tape
Quantity	4000pcs
Direction of feed	E2 The direction is the pin 1 of product is at the upper left when you hold reel on the left hand and you pull out the tape on the right hand



Revision History

Date	Revision	Changes
14.Mar.2017	001	New Release
22.Jan.2018	002	P.14 Update Physical Dimension, Tape and Reel Information.

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(Note1) Medical Equipment Classification of the Specific Applications

JAPAN	USA	EU	CHINA
CLASS III	CLASS III	CLASS II b	CLASS III
CLASS IV		CLASS III	

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 - Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
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 - Use of the Products in places subject to dew condensation
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- De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- Confirm that operation temperature is within the specified range described in the product specification.
- ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

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- In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

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 - [d] the Products are exposed to high Electrostatic
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3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
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